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Amended claims

- A hot melt adhesive composition comprising, by weight of the hot melt Claim 1. adhesive composition,
- about 5 weight percent to about 60 weight percent of an ethylene vinyl acetate a) copolymer having a vinyl acetate content of about 30 weight percent to 50 weight percent and a melt index of about 700 to 4,000 dg/min;
 - about 5 weight percent to about 60 weight percent of a tackifier; and b)
- about 15 weight percent to about 55 weight percent of a wax with a c) melting point of about 125°F to 180°F;

wherein the hot melt composition can be applied at a temperature of 200°F to 300°F.

- An adhesive according to Claim 1 wherein the wax is paraffin wax or Claim 6. synthetic wax.
- A hot melt adhesive composition comprising, by weight of the hot melt Claim 8. adhesive composition,
- a) about 35 weight percent of an ethylene vinyl acetate copolymer with about 40 weight percent vinyl acetate and having a melt index of at about 1,000;
- b) about 30 weight percent of a tackifier selected from the group consisting of terpene, terpene phenolic, modified terpenes, and combinations thereof;
- c) about 5 weight percent of at least one additional tackifier selected from the group consisting of pentaerythritol, hydrogenated glycerol, and combinations thereof;
- d) about 30 weight percent of a wax with a melting point of about 150°F; wherein the hot melt composition can be applied at a temperature of 200°F to 300°F.
- An adhesive according to Claim 3 which comprises a terpene phenolic Claim 10. tackifier.

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- Claim 11. An adhesive according to Claim 1 which comprises about 35 weight percent to about 45 weight percent of an ethylene vinyl acetate copolymer.
- Claim 12. A method of bonding substrates together, said method comprising applying, at an application temperature of 200°F to 300°F, the hot melt adhesive composition of claim 1 to a first substrate, bringing a second substrate in contact with the composition applied to the first substrate, whereby the first substrate becomes bonded to the second substrate.